

# TSF70R360

## 700V N-Channel MOSFET

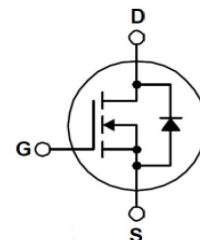
**TSF70R360**

### Description

The 70R360 is power MOSFET using Truesemi's advanced super junction technology that can realize very low on-resistance and gate charge. It will provide much high efficiency by using optimized charge coupling technology. These user friendly devices give an advantage of Low EMI to designers as well as low switching loss.

### Features

- 13A,700V,Max.RDS(on)=0.36Ω @ VGS =10V
- CRM(CQ) Super\_Junction technology
- Much lower Ron\*A performance for On-state efficiency
- Much lower FOM for fast switching efficiency



### Absolute Maximum Ratings

T<sub>C</sub>=25°C unless otherwise specified

Symbol	Parameter		TSF70R360	Units
V <sub>DSS</sub>	Drain-Source Voltage		700	V
V <sub>GS</sub>	Gate-Source Voltage		± 30	V
I <sub>D</sub>	Drain Current	T <sub>C</sub> = 25°C	13	A
		T <sub>C</sub> = 100°C	8	A
I <sub>DM</sub>	Pulsed Drain Current (T <sub>C</sub> = 25°C, t <sub>p</sub> limited by T <sub>jmax</sub> )		52	A
E <sub>AS</sub>	Avalanche energy, single pulse (L=30mH, R <sub>g</sub> =50Ω)		90	mJ
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25°C)		25	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C

### Thermal Resistance Characteristics

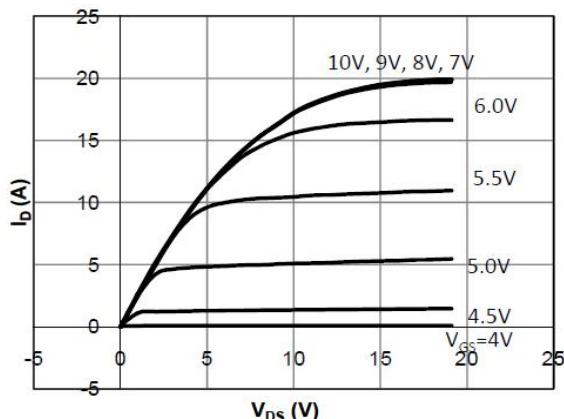
Symbol	Parameter	Value	Units
R <sub>ejc</sub>	Thermal Resistance,Junction-to-Case.Max	5.04	°C/W
R <sub>eja</sub>	Thermal Resistance,Junction-to-Ambient.Max	56	°C/W

**Electrical Characteristics**  $T_c=25^\circ\text{C}$  unless otherwise specified

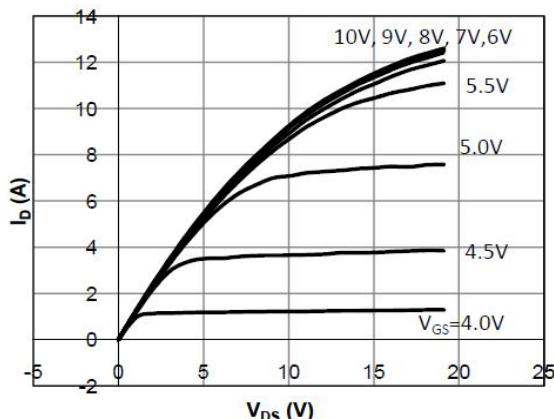
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$	3.0	--	4.0	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}$ , $I_D = 3 \text{ A}$	--	0.33	0.36	$\Omega$
$g_{fs}$	Forward transfer conductance	$V_{DS} = 20 \text{ V}$ , $I_D = 6 \text{ A}$	--	10	--	S
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$	700	--	--	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 700 \text{ V}$ , $V_{GS} = 0 \text{ V}$	--	--	1	$\mu\text{A}$
		$V_{DS} = 700 \text{ V}$ , $T_c = 125^\circ\text{C}$	--	10	--	$\mu\text{A}$
$I_{GSSF}$	Gate-Body Leakage Current,Forward	$V_{GS} = 30 \text{ V}$ , $V_{DS} = 0 \text{ V}$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current,Reverse	$V_{GS} = -30 \text{ V}$ , $V_{DS} = 0 \text{ V}$	--	--	-100	nA
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = 100 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $f = 1.0 \text{ MHz}$	--	742	--	pF
$C_{oss}$	Output Capacitance		--	35	--	pF
$C_{rss}$	Reverse Transfer Capacitance		--	0.5	--	pF
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Time	$T_j = 25^\circ\text{C}$ , $V_{GS} = 10 \text{ V}$ , $I_D = 6 \text{ A}$ , $V_{DS} = 400 \text{ V}$ , $R_g = 27 \Omega$	--	20	--	ns
$t_r$	Turn-On Rise Time		--	26	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	105	--	ns
$t_f$	Turn-Off Fall Time		--	32	--	ns
$R_G$	Gate resistance	$V_{GS} = 0 \text{ V}$ , $V_{DS} = 0 \text{ V}$ , $f = 1 \text{ MHz}$	--	9.3	--	$\Omega$
$Q_g$	Total Gate Charge	$V_{GS} = 10 \text{ V}$ , $V_{DS} = 480 \text{ V}$ , $I_D = 6 \text{ A}$ , $f = 1 \text{ MHz}$	--	26	--	nC
$Q_{gs}$	Gate-Source Charge		--	3.7	--	nC
$Q_{gd}$	Gate-Drain Charge		--	13.8	--	nC
<b>Source-Drain Diode Maximum Ratings and Characteristics</b>						
$V_{SD}$	Source-Drain Diode Forward Voltage	$I_s = 6 \text{ A}$ , $V_{GS} = 0 \text{ V}$	0.5	0.83	1.0	V
$t_{rr}$	Reverse Recovery Time	$I_{sd} = 6 \text{ A}$ $dI/dt = 100 \text{ A/us}$ , $V_{ds} = 100 \text{ V}$	--	210	--	ns
$Q_{rr}$	Reverse Recovery Charge		--	2.05	--	uC

## Typical Performance Characteristics

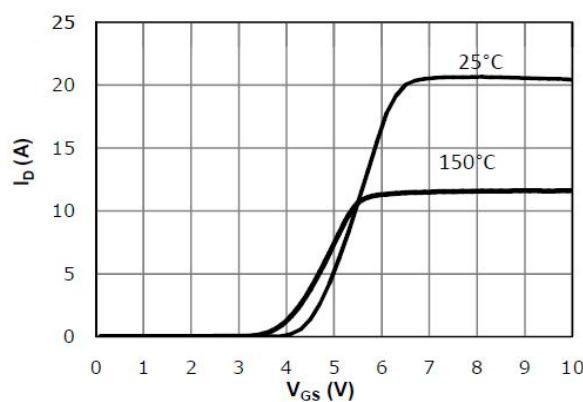
**Fig 1. Output Characteristics ( $T_j=25^\circ\text{C}$ )**



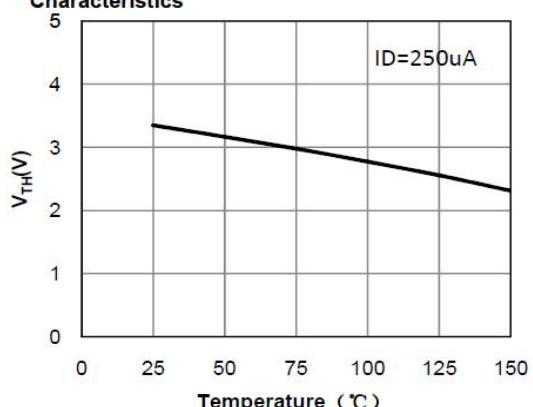
**Fig 2. Output Characteristics ( $T_j=150^\circ\text{C}$ )**



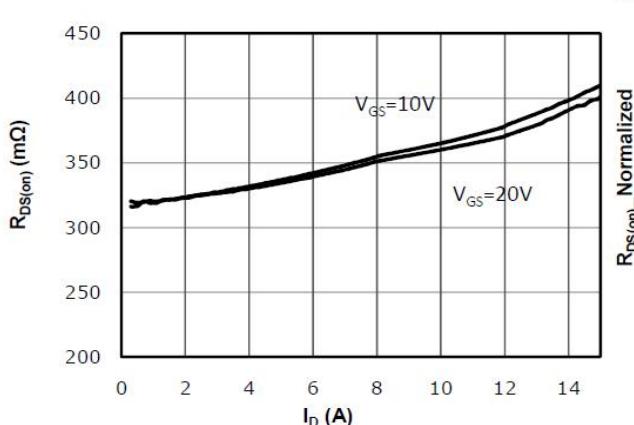
**Fig 3: Transfer Characteristics**



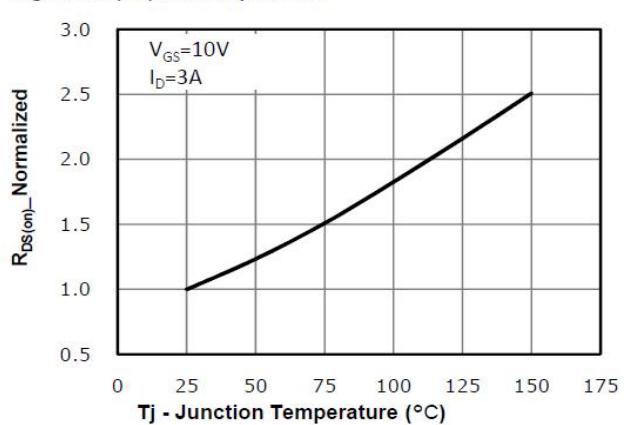
**Fig 4:  $V_{TH}$  Vs  $T_j$  Temperature Characteristics**

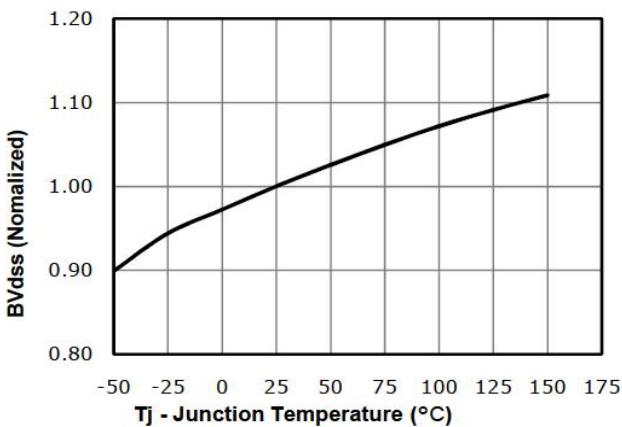
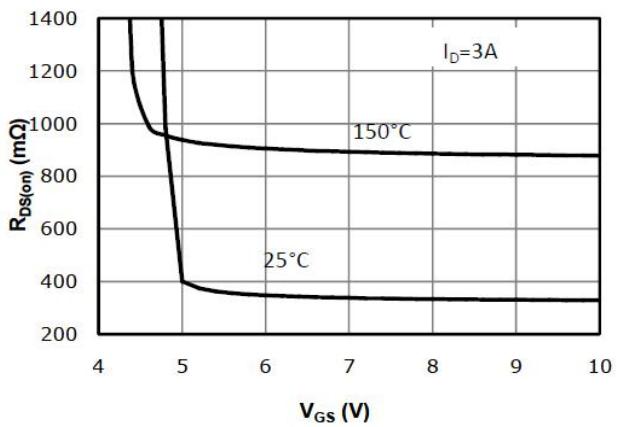
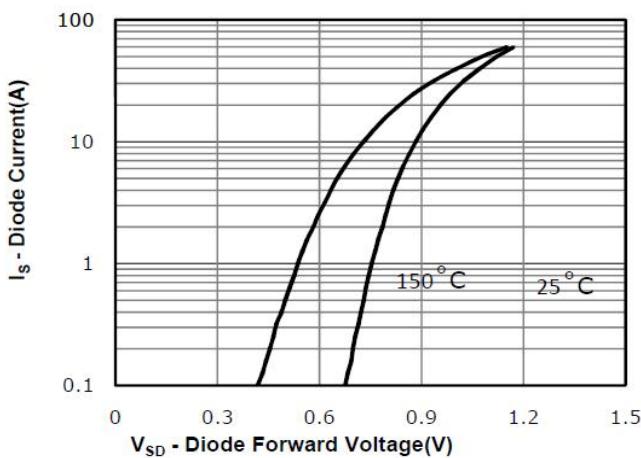
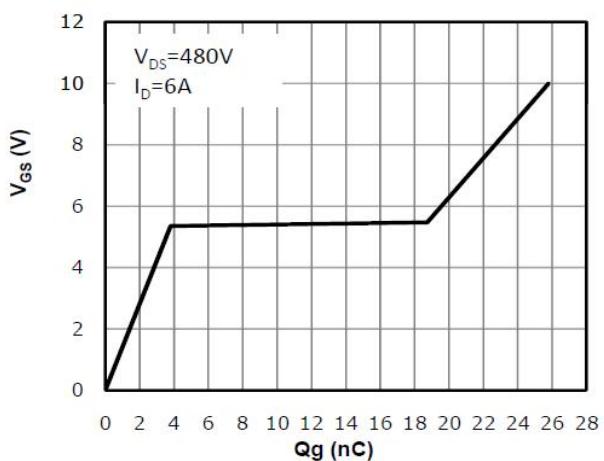
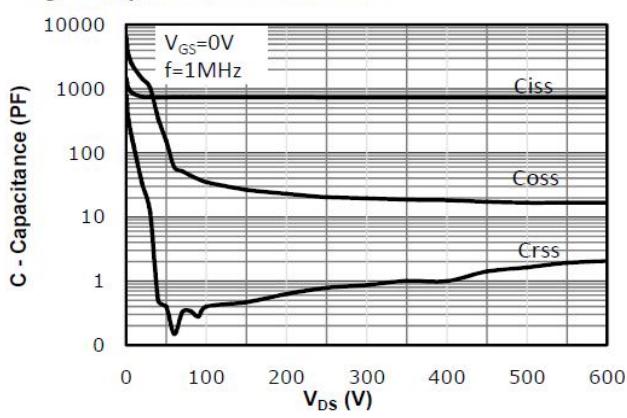
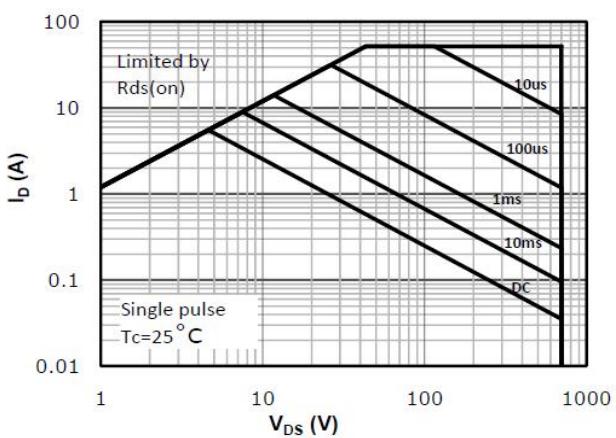


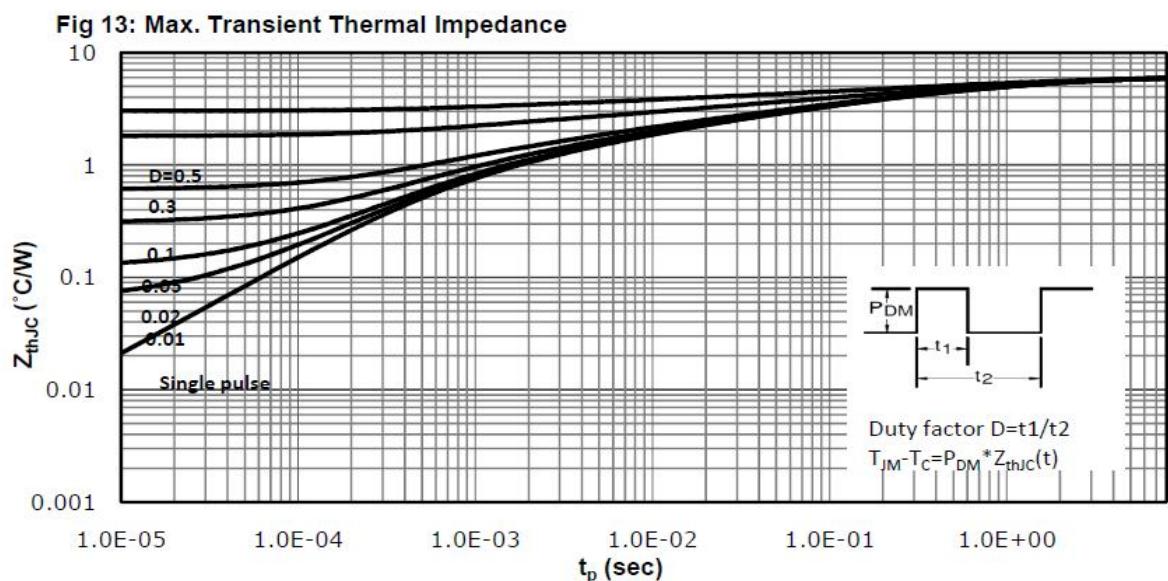
**Fig 5:  $R_{DSON}$  Vs  $I_{DS}$  Characteristics( $T_c=25^\circ\text{C}$ )**



**Fig 6:  $R_{DSON}$  vs. Temperature**

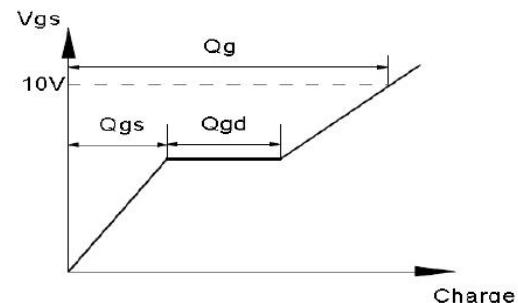
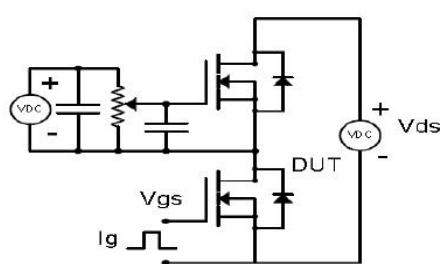


**Fig 7: BV<sub>DSS</sub> vs. Temperature****Fig 8: R<sub>d(on)</sub> vs Gate Voltage****Fig 9: Body-diode Forward Characteristics****Fig 10: Gate Charge Characteristics****Fig 11: Capacitance Characteristics****Fig 12: Safe Operating Area**

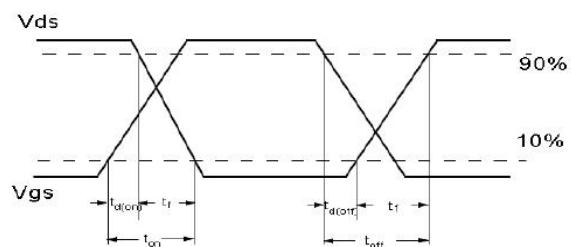
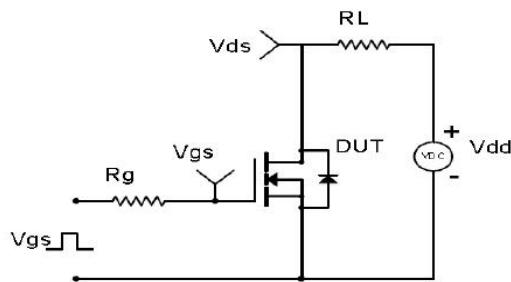


**Test Circuit & Waveform**

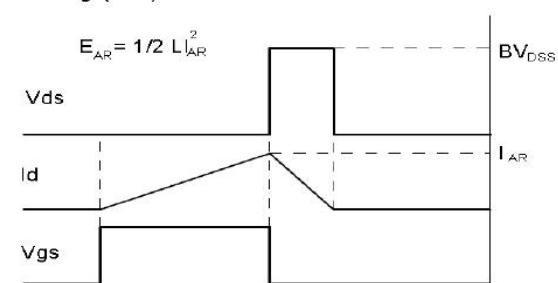
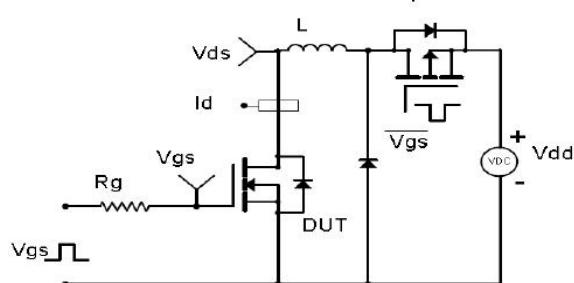
Gate Charge Test Circuit &amp; Waveform



Resistive Switching Test Circuit &amp; Waveforms



Unclamped Inductive Switching (UIS) Test Circuit &amp; Waveforms



Diode Recovery Test Circuit &amp; Waveforms

